



## Rosin Free and Lead Free Solder Wire

### Sn99.3Cu0.7 - "HC1"

A high quality binary alloy for mechanical or electrical applications which demand lead free solders composed of tin and copper. It is an efficient suitable alternative to Tin/Lead. Other benefits are increased joint strength and clear residues.

The internal inorganic water-soluble flux is rosin free.

#### Chemical Characteristics

Tin-Copper binary Alloy

Amount of Tin:	99.3%
Amount of Copper:	0.7%

Tin and lead of first smelting, copper purity of 99.90%

Chart of typical maximum impurities:

Sb	Pb	Ag	Cd	Bi
0.05	0.05	0.005	0.002	0.01

Fe	Zn	Al	As	Others
0.02	0.001	0.001	0.01	0.05

#### Physical Characteristics, standard:

*ALLOY: Sn99.3Cu0.7	
Melting point	227°C (Eutectic)
Specific weight	7.3 g/cm <sup>3</sup>
Wire diameter	From 0.5mm to 5mm
Working temperature	350 to 450 °C

#### \*FLUX

- Rosin free
- Water soluble / inorganic
- Halides: 1.3%
- Acid value: 50 +/- 10
- Good wetting on zinc, stainless steel and nickel
- It is recommended that the residues are removed in most applications.

#### Other Characteristics

**Supplied on spools:** 250g and 500g, others on request

**Packed in cartons of:** 5kg and 10kg, others on request

**Identification:** Boxes and spools carry product information labels

**Quality assurance:** Certificates of Conformity can be issued for each shipment batch if requested at the time of ordering.

**Shelf life:** 12 months under ambient conditions